

ABSTRACT OF THE DISCLOSURE

A selective sputtering method and resulting substrate are provided.

This may involve obtaining a substrate and identifying a die placement area and a keep out area of the substrate. A protective area may be formed over the substrate between the die placement area and the keep out area. This may be done using a selective sputtering process. Underfill material may be provided over at least the die placement area of the substrate without the underfill material flowing to the keep out area based on the surface roughness of the keep out area.

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